

RZ/A2M Group

RZ/A2M Simple Applications Package (IAR Embedded Workbench for ARM) V3.00 Release Note

Introduction

This Software Package has several simple applications for RZ/A2M.

The Software Package shows how easy it is to create a professional, user-friendly and platform-independent user interface for your product. The entire application source code is included in the workspace enabling the Software Package to be ported to the platform of your choice.

This package is one of RZ/A2M Software Package. RZ/A2M Software Package is a software development kit for the RZ/A2M that supports various RZ/A2M functions such as DRP (Dynamically Reconfigurable Processor), camera input, LCD output, and image adjustment. This package has the structure of the red frame in the following figure. However, device driver and middleware are only included what is necessary for the sample application.

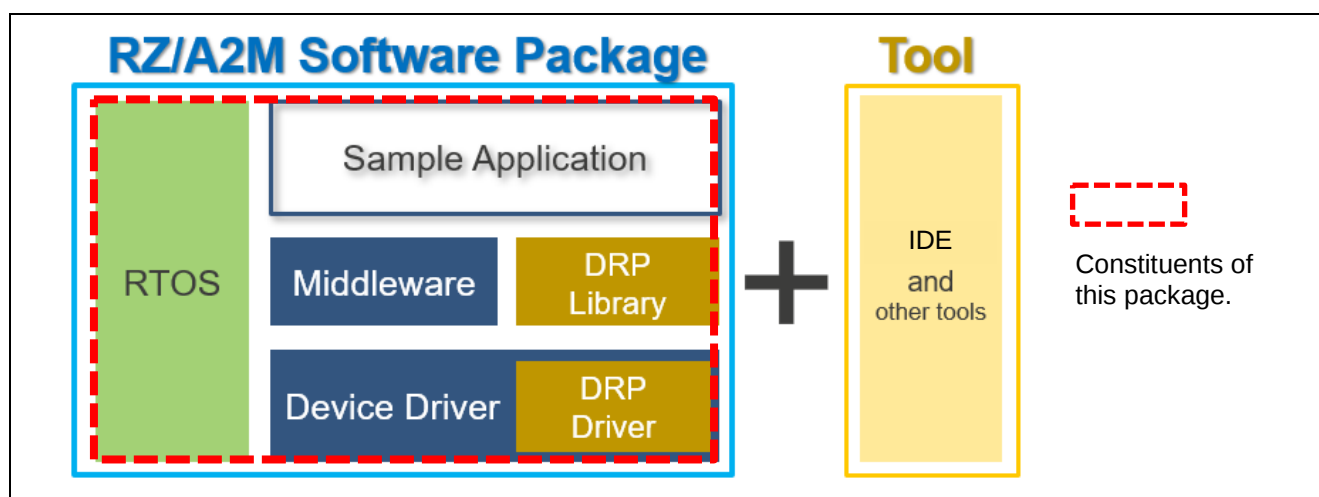
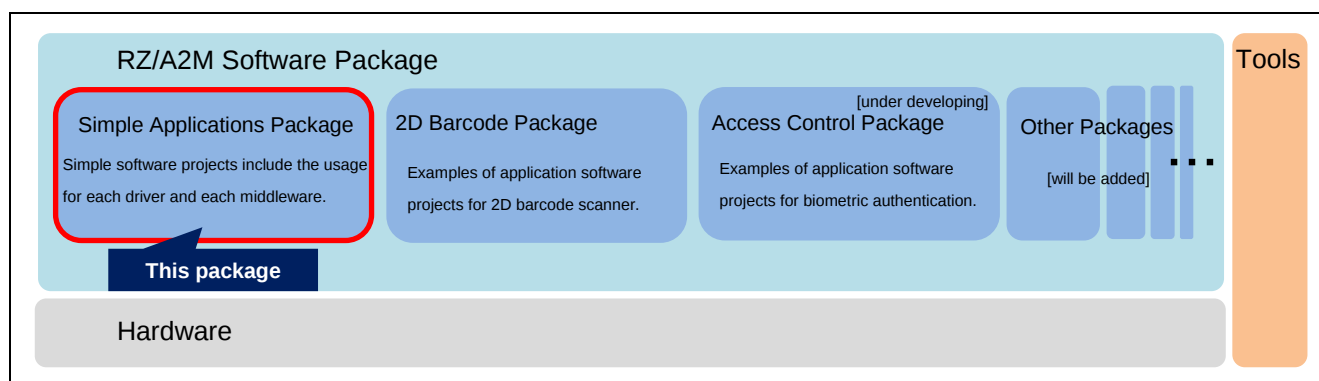


Figure below shows the relation of RZ/A2M Software Package and this package. For details, refer following URL:

<https://www.renesas.com/products/software-tools/software-os-middleware-driver/software-package/rza2-software-development-kit-free-rtos/iarcompiler.html>



Note that each software project includes only driver software and middleware used by each application.

Following sample applications are bundled in this package.

Example of initialization:

This sample is a simple sample program that blinks the LED on the RZ/A2M evaluation board. You can use this application as base project of your product.

Example of FreeRTOS:

This sample is a simple sample program that blinks the LED on the RZ/A2M evaluation board. In this sample, FreeRTOS is used. You can use this application as base project of your product.

Camera and Display sample application:

This program captures video from the MIPI CSI-2 interface camera module bundled in RZ/A2M Evaluation Board Kit and displays it on the display. In this sample, FreeRTOS is used.

DRP basic sample program

The DRP basic sample program provides the following sample. In this sample, FreeRTOS is used.

DRP Basic Operation Sample Program

Converts the input image from MIPI camera to grayscale image using DRP and outputs to display.

Ethernet sample program

This sample program connects the RZ/A2M evaluation board and network, outputs data to the Echo server, and confirms the response. In this sample, FreeRTOS is used.

Example of Low power mode

This sample program handles the stand-by mode process. (Stand-by in/out). In this sample, FreeRTOS is NOT used.

Pmod ESP32 Wi-Fi Sample program

This sample program transmits the JPEG data converted from captured image from MIPI camera using Digilent Pmod ESP32 module. In this sample, FreeRTOS is used.

Environment

- Target Device: RZ/A2M
- Target Board Kit: RZ/A2M Evaluation Board Kit (RTK7921053S00000BE)
- IDE: IAR Embedded Workbench® for ARM v8.40.1 or later (hereinafter called "EWARM")
- Tool Chain: IAR C/C++ Compiler™

The IDE is available from the following site.

<https://www.iar.com/iar-embedded-workbench/#!/?architecture=Arm>

Contents

1. Package Contents4

1.1 Software 4

1.2 Documents 4

2. Folder Structure5

3. How to use the projects bundled in this package6

4. Reference Application Notes6

5. Restrictions.....6

6. Precautions7

7. Used open source software and licenses.....8

Revision History9

1. Package Contents

1.1 Software

This package contains the following software.

Table 1-1 Software of this package

No	Name	File
1	RZ/A2M Group Example of Initialization	rza2m_blinky_sample_osless_iar.zip
2	RZ/A2M Group Example of FreeRTOS	rza2m_blinky_sample_freertos_iar.zip
3	RZ/A2M Group Camera and Display sample application	rza2m_cam_and_disp_sample_freertos_iar.zip
4	RZ/A2M Group DRP basic sample program	rza2m_drp_basic_sample_freertos_iar.zip
5	RZ/A2M Group Ethernet sample program	rza2m_ethernet_sample_freertos_iar.zip
6	RZ/A2M Group Example of Low power mode	rza2m_lpm_sample_osless_iar.zip
7	RZ/A2M Group Pmod ESP32 Wi-Fi Sample program	rza2m_wifi_pmod_esp32_sample_freertos_iar.zip

1.2 Documents

This package contains the following documents.

Table 1-2 Documents of this package

No	Title	Document Number
1	RZ/A2M Group RZ/A2M Simple Applications Package (IAR Embedded Workbench for ARM) V3.00 Release Note	R01AN4832 (This document)

Also, each project indicated in Table 1-1 includes the sample program's application notes.

Each driver folder includes the document for the driver.

The documentation for these drivers is written for the GCC compiler. Replace the Operation Confirmation Conditions with the following.

Integrated development environment	EWARM v8.40.1
C compiler	IAR C/C++ Compiler for ARM Release: <pre>--endian=little --cpu=Cortex-A9 -e --fpu=VFPv3 --dlib_config --cpu_mode arm -Oh</pre> Debug: <pre>--debug --endian=little --cpu=Cortex-A9 -e --fpu=VFPv3 --dlib_config --cpu_mode arm -On</pre>

2. Folder Structure

Folder structure of this package and outline of contents are shown in Figure 2.1.

TOP	: top folder
+---rza2m_blinky_sample_osless_iar.zip	: RZ/A2M Group Example of Initialization
+---rza2m_blinky_sample_freertos_iar.zip	: RZ/A2M Group Example of FreeRTOS
+---rza2m_cam_and_disp_sample_freertos_iar.zip	: RZ/A2M Group Camera and Display sample
+---rza2m_drp_basic_sample_freertos_iar.zip	: RZ/A2M Group DRP basic sample program
+---rza2m_ethernet_sample_freertos_iar.zip	: RZ/A2M Group Ethernet sample program
+---rza2m_lpm_sample_osless_iar.zip	: RZ/A2M Group Example of Low power mode
+---rza2m_wifi_pmod_esp32_sample_freertos_iar.zip	: RZ/A2M Group Pmod ESP32 Wi-Fi Sample program
+---r01an4832ej0300-rza2m-simple-apl-swpkg-iar.pdf	: RZ/A2M Group RZ/A2M Simple Applications Package (IAR Embedded Workbench for ARM) V3.00 Release Note (this document)
+---r01an4832jj0300-rza2m-simple-apl-swpkg-iar.pdf	: RZ/A2M Group RZ/A2M Simple Applications Package (IAR Embedded Workbench for ARM) V3.00 Release Note (Japanese)
+---r01qs0034ej0100-rza2m-quick-guide-iar.pdf	: RZ/A2M Group RZ/A2M Software Package (IAR Embedded Workbench for ARM) Quick Start Guide (English)
+---r01qs0034jj0100-rza2m-quick-guide-iar.pdf	: RZ/A2M Group RZ/A2M Software Package (IAR Embedded Workbench for ARM) Quick Start Guide (Japanese)

Figure 2.1 Folder Structure

3. How to use the projects bundled in this package

Regarding how to use, refer to the documents in each folder in this package.

4. Reference Application Notes

Following is the list of application notes related to this software package.

RZ/A2M Group RZ/A2M Software Core Package (R01AN4775).

Drivers and middleware for RZ/A2M that can be added to the project bundled in this package.

Note: This is a package for the GCC compiler.

5. Restrictions

The Restrictions of this package are shown as follow.

Table 5-1 Restrictions

No.	Type	Description
1	DRP Driver*	The following API Functions are not supported. - R_DK2_Uninitialize - R_DK2_Inactivate If these functions are called, these functions occur an error and return "R_DK2_ERR_INTERNAL".
2	DRP Driver *	The function that load the configuration data in background is not supported. This function validates when argument "pload" of R_DK2_Load Function is set to anything other than NULL. In the version in this package this function occurs an error and return "R_DK2_ERR_INTERNAL".
3	DRP Driver *	R_DK2_Load Function notifies the return value "R_DK2_ERR_DEVICE", when detects a transfer error of the configuration data. In the version in this package this function is not supported.
4	DRP Driver *	Processing Completion Callback Function notifies the argument "result" is "R_DK2_ERR_DEVICE", when detects a transfer error in DRP. In the version in this package this function is not supported.
5	DRP Driver *	Processing Completion Callback Function notifies the argument "result" is "R_DK2_ERR_STOPPED", when detects a transfer stopped by calling R_DK2_Unload Function of R_DK2_Inactivate Function. In the version in this package this function is not supported.

Note 1 Please refer to "RZ/A2M Group DRP Driver User's Manual(R01US0355)" for details of DRP Driver's function.

6. Precautions

The Precautions of this package are shown as follow.

Table 6-1 Precautions

No.	Type	Description
1	Environment	To avoid build error, expand the project to the folder with short full-path.
2	Environment	To avoid build error, expand the project to the folder without multi-byte character.
3	Emulator	The default emulator for the sample project is I-jet. Please change the project settings when using J-Link.

7. Used open source software and licenses

Open source software used in this package and license of them are shown as following:

- FreeRTOS™ is a trade mark of Amazon Web Services, Inc.
- FreeRTOS is used under MIT license described in following site:
<https://www.freertos.org/a00114.html>
- Amazon FreeRTOS is used under MIT license described in following site:
<https://github.com/aws/amazon-freertos/blob/master/LICENSE>
<https://aws.amazon.com/freertos/faqs/>
- mbedTLS is used under the Apache License, Version 2.0 described in following site:
<http://www.apache.org/licenses/LICENSE-2.0>

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jul. 31, 2019	-	First Edition issued
2.00	Nov. 29, 2019	P4-5	Added an application that is included in the package Ethernet sample program
3.00	Feb. 28, 2020	P4-5	Added an application that is included in the package Example of Low power mode Pmod ESP32 Wi-Fi Sample program

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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